Qualcomm

RF360
Europe GmbH

Data sheet

BAW filter
WLAN 2G; Bluetooth

Series/type:	B2614
Ordering code:	B39242B2614P810
Date:	March 11, 2019
Version:	2.1

DCN: 80-PA243-310 Rev. A

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Table of contents

1 Application....4
2 Features....4
3 Package....5
4 Pin configuration....5
5 Matching circuit....6
6 Characteristics....7
7 Maximum ratings....9
8 Transmission coefficient....10
9 Transmission coefficient (WLAN)....11
10 Transmission coefficient (integrated)....12
11 Reflection coefficients....13
12 Packing material....14
13 Marking....17
14 Soldering profile....18
15 Annotations....19
16 Cautions and warnings....20
17 Important notes....21

1 Application

- Low-loss BAW RF single filter for Bluetooth/WLAN systems
- Low insertion attenuation

2 Features

- Package size $1.1_{\pm 0.1}$ mm × $0.9_{\pm 0.1}$ mm
- Package height 0.45 mm (max.)
- Approximate weight 5 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family (Grade 1: −40 °C to +125 °C)

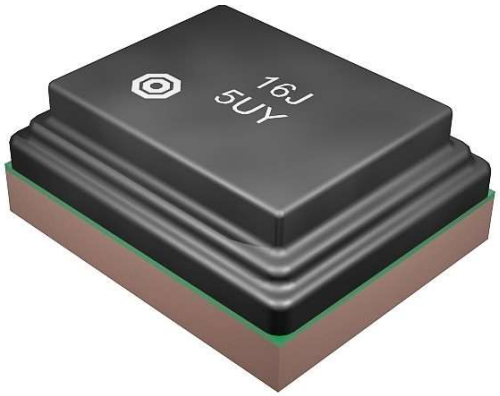


Figure 1: Picture of component with example of product marking.

3 Package

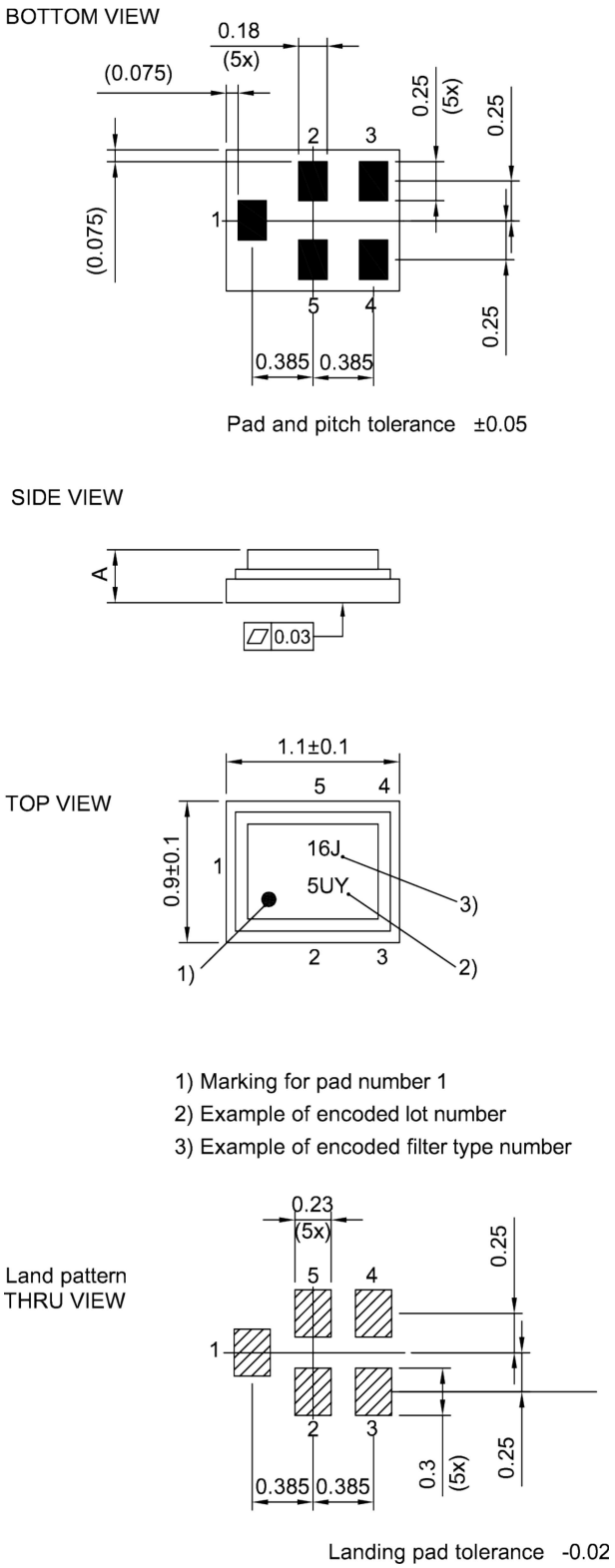


Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 20).

4 Pin configuration

- 1 Input
- 4 Output
- 3 Shaping
- 2, 5 Ground

5 Matching circuit

- L_{g3} = 0.5 nH
- L_{s1} = 1.4 nH
- L_{s4} = 1.5 nH

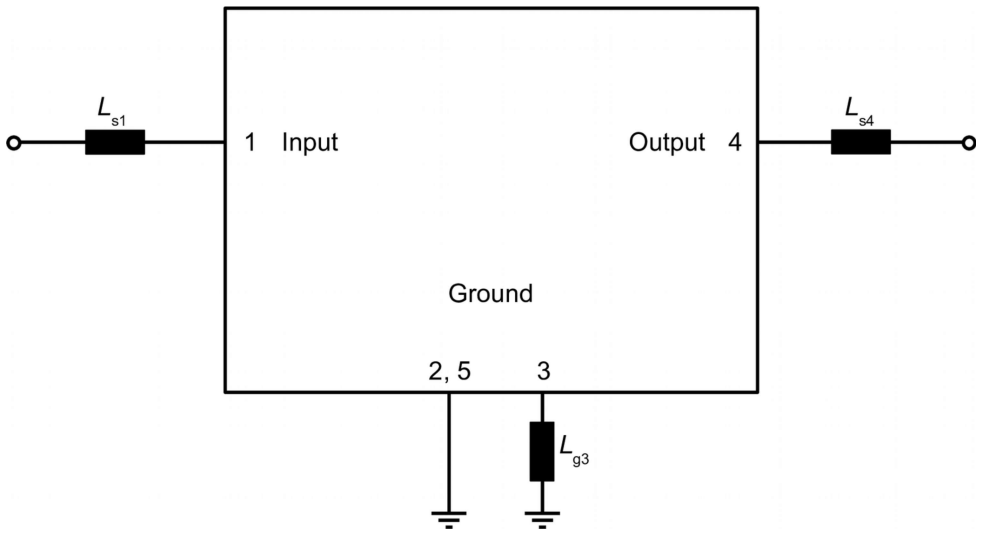


Figure 3: Schematic of matching circuit.

6 Characteristics

Temperature range for specification T_{SPEC} = −40 °C ... +105 °C
Input terminating impedance Z_{IN} = 50 Ω + 1.4 nH[1)]
Output terminating impedance Z_{OUT} = 50 Ω + 1.5 nH[1)]

Characteristics				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Maximum insertion attenuation – WLAN			$\alpha_{WLAN,max}$[2)]				
WLAN ch1	2403.1 ... 2420.9	MHz		—	1.6	2.5	dB
WLAN ch2	2408.1 ... 2425.9	MHz		—	1.5	2.0	dB
WLAN ch3-ch11	2413.1 ... 2470.9	MHz		—	1.2	1.8	dB
WLAN ch12	2458.1 ... 2475.9	MHz		—	1.3	2.1	dB
WLAN ch13	2463.1 ... 2480.9	MHz		—	1.5	2.7	dB
Maximum insertion attenuation – BT			$\alpha_{BT,max}$[3)]				
	2401.5 ... 2480.5	MHz		—	1.5	2.0	dB
Amplitude ripple (p-p)			Δα				
WLAN ch1	2403.1 ... 2420.9	MHz		—	0.6	5.0	dB
WLAN ch2	2408.1 ... 2425.9	MHz		—	0.5	1.5	dB
WLAN ch3	2413.1 ... 2430.9	MHz		—	0.4	1.2	dB
WLAN ch4-ch10	2418.1 ... 2465.9	MHz		—	0.2	1.2	dB
WLAN ch11	2453.1 ... 2470.9	MHz		—	0.6	1.2	dB
WLAN ch12	2458.1 ... 2475.9	MHz		—	1.0	1.6	dB
WLAN ch13	2463.1 ... 2480.9	MHz		—	1.0	6.0	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	2403.1 ... 2475.9	MHz		—	1.6	2.3	
	2463.1 ... 2480.9	MHz		—	1.6	2.5[4)]	
@ output port	2403.1 ... 2475.9	MHz		—	1.6	2.3	
	2463.1 ... 2480.9	MHz		—	1.6	2.5[4)]	
Minimum attenuation							
	10 ... 800	MHz	α_{min}	30	35	—	dB
	800 ... 1805	MHz	α_{min}	25	31	—	dB
	1805 ... 2170	MHz	α_{min}	25	32	—	dB
	2170 ... 2300	MHz	α_{min}	28	34	—	dB
	2300 ... 2360	MHz	α_{min}	38	45	—	dB
	2360 ... 2365	MHz	$\alpha_{INT,min}$[5)]	38	52	—	dB
	2365 ... 2370	MHz	$\alpha_{INT,min}$[5)]	35	43	—	dB
	2370 ... 2375	MHz	$\alpha_{INT,min}$[5)]	34	39	—	dB
	2375 ... 2380	MHz	$\alpha_{INT,min}$[5)]	22	40	—	dB
	2380 ... 2385	MHz	$\alpha_{INT,min}$[5)]	9	39	—	dB
	2496 ... 2501	MHz	$\alpha_{INT,min}$[5)]	12	45	—	dB
	2500 ... 2505	MHz	$\alpha_{INT,min}$[5)]	35[6)]	52	—	dB
	2500 ... 2505	MHz	$\alpha_{INT,min}$[5)]	26	52	—	dB

Characteristics				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
	2505... 2570	MHz	α_{min}	35	39	—	dB
	2570... 2620	MHz	α_{min}	30	35	—	dB
	2620... 2690	MHz	α_{min}	30	34	—	dB
	2690... 2900	MHz	α_{min}	22	29	—	dB
	2900... 3400	MHz	α_{min}	28	36	—	dB
	3400... 3800	MHz	α_{min}	28	44	—	dB
	3800... 4100	MHz	α_{min}	10	20	—	dB
	4100... 4800	MHz	α_{min}	25	34	—	dB
	4800... 5150	MHz	α_{min}	20	33	—	dB
	5150... 5850	MHz	α_{min}	20	30	—	dB

1) See Sec. Matching circuit (p. 6).
2) Average over each WLAN channel with band width of 17.8 MHz.
3) Averaged value over whole pass band with band width of 79 MHz due to frequency hopping in Bluetooth mode.
4) Valid for temperature T = −40 °C...+85 °C.
5) Integrated over 5 MHz.
6) Valid for temperature T = +25 °C...+105 °C.

7 Maximum ratings

Operable temperature	T_{OP} = −40 °C ... +125 °C	
Storage temperature	T_{STG} [1] = −40 °C ... +125 °C	
DC voltage	$\|V_{DC}\|$ [2] = 0 V (max.)	
Input power	P_{IN}	
@ input port: 2403.1 ... 2480.9 MHz	25 dBm	17.8 MHz WLAN signal for 5000 h @ 85 °C. Source and load impedance 50Ω. [3]
@ input port: other frequency ranges	10 dBm	17.8 MHz WLAN signal for 5000 h @ 85 °C. Source and load impedance 50Ω.

1) Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.
2) In case of applied DC voltage blocking capacitors are mandatory.
3) Expected lifetime according to accelerated power durability simulation, and wear out models.

8 Transmission coefficient

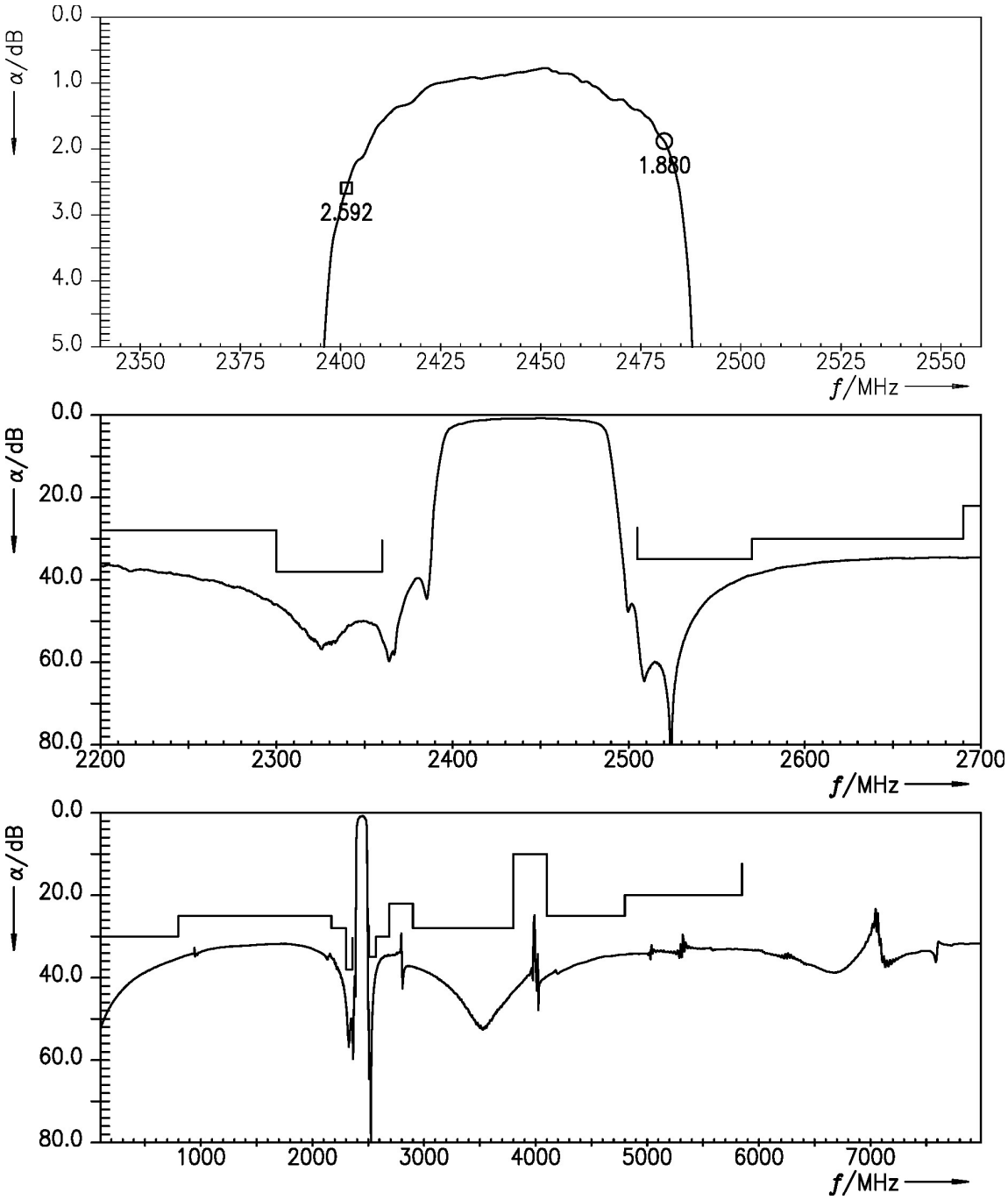


Figure 4: Attenuation .

9 Transmission coefficient (WLAN)

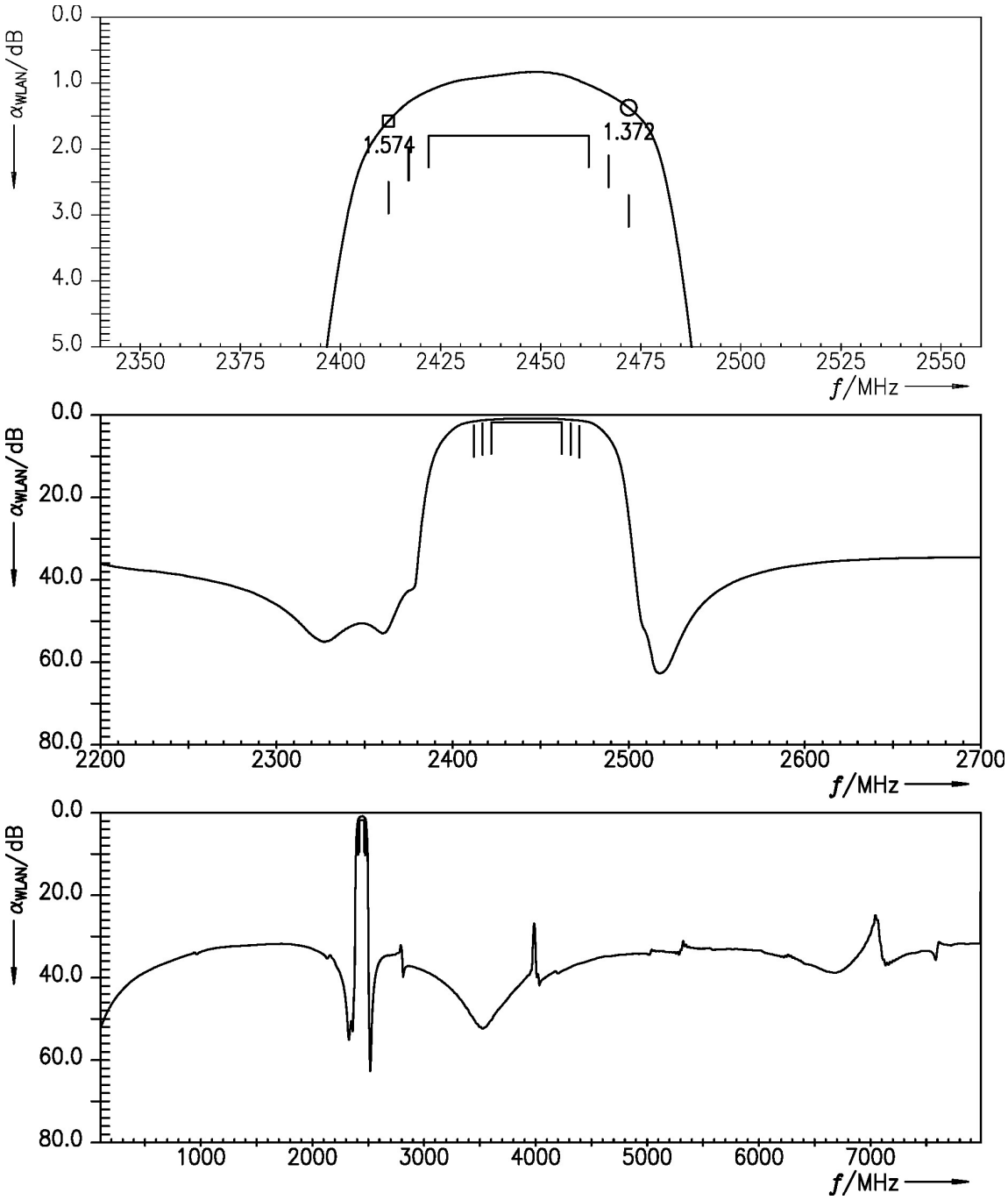


Figure 5: Attenuation (WLAN) (integration window = 17.8 MHz) .

10 Transmission coefficient (integrated)

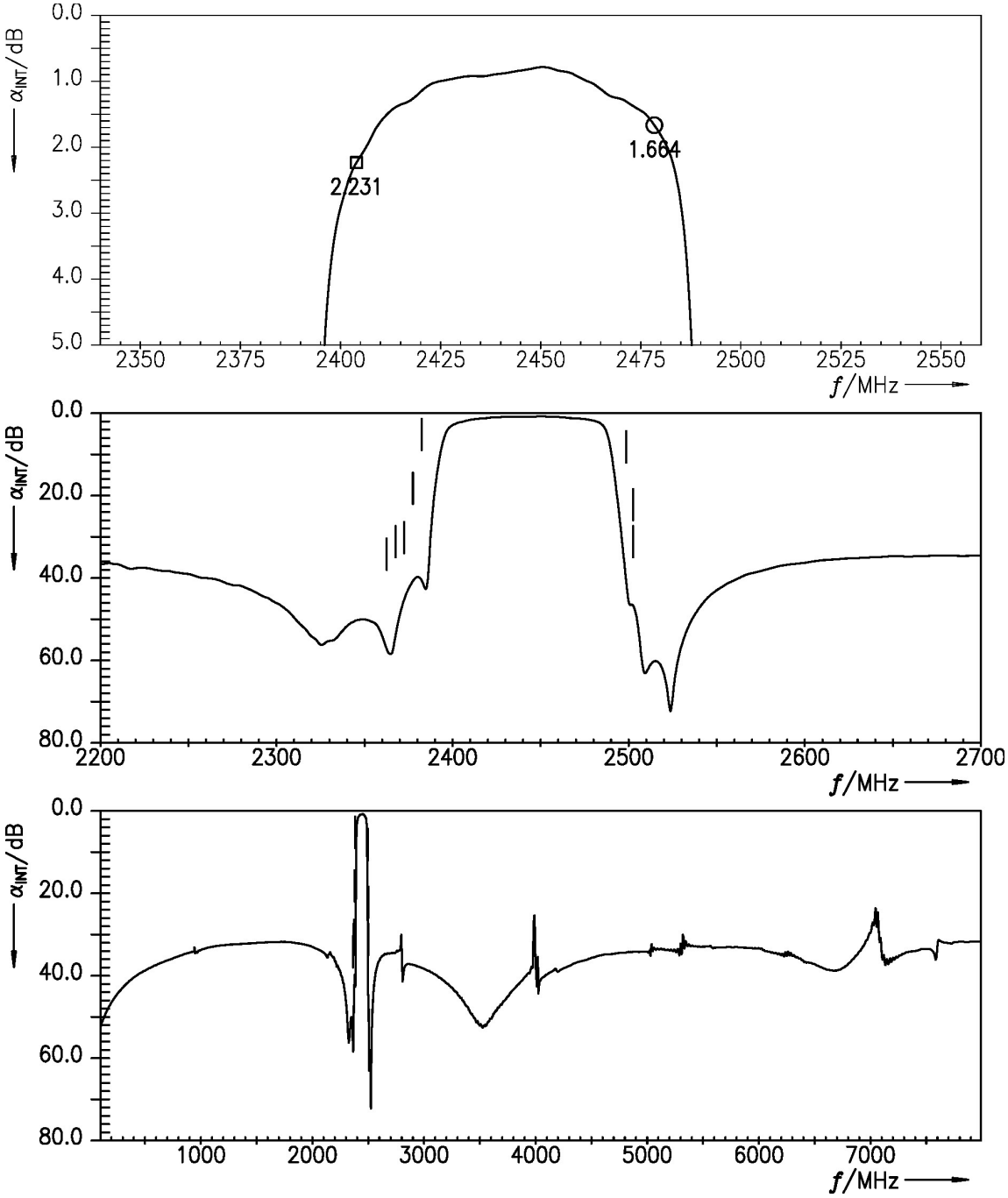


Figure 6: Integrated attenuation (integration window = 5 MHz) .

11 Reflection coefficients

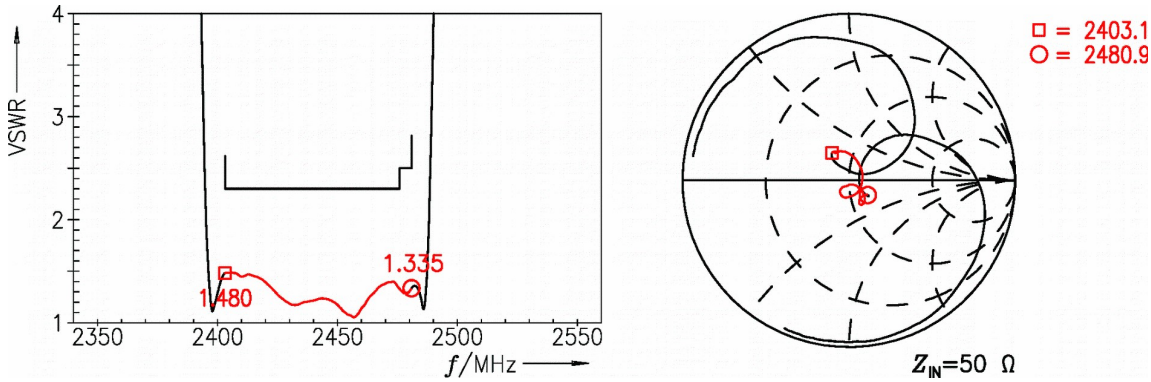


Figure 7: Reflection coefficient at input port.

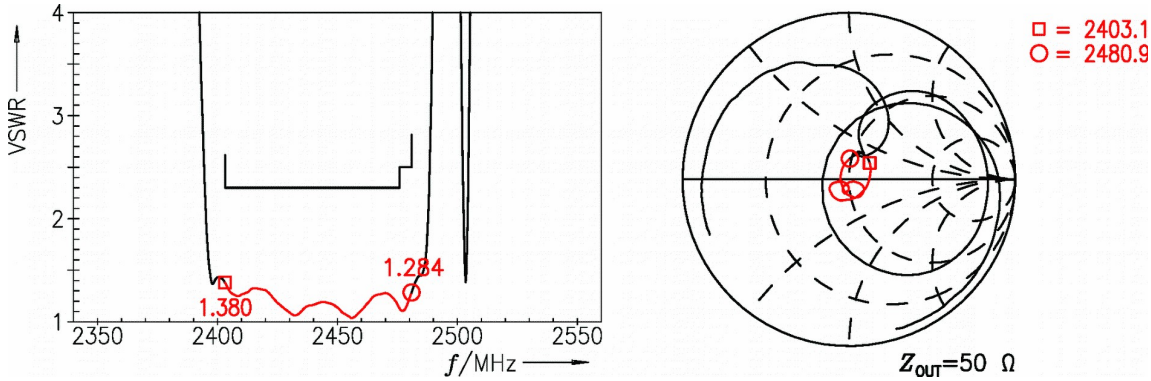


Figure 8: Reflection coefficient at output port.

12 Packing material

12.1 Tape

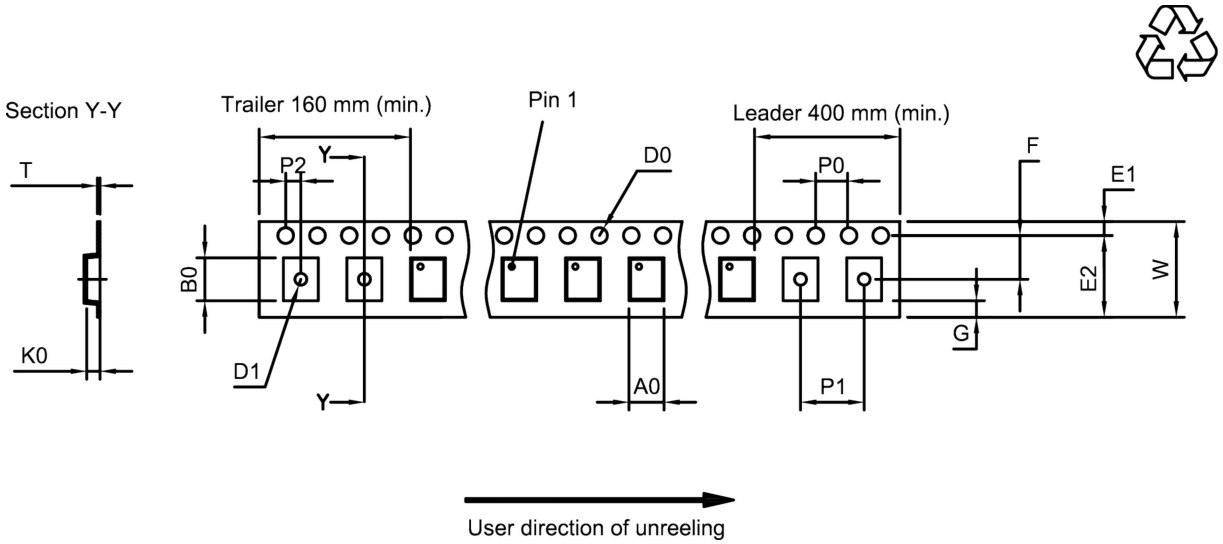


Figure 9: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A_0	$1.02_{\pm 0.05}$ mm
B_0	$1.22_{\pm 0.05}$ mm
D_0	$1.55_{\pm 0.05}$ mm
D_1	$0.55_{\pm 0.1}$ mm
E_1	$1.75_{\pm 0.1}$ mm

E_2	6.25 mm (min.)
F	$3.5_{\pm 0.05}$ mm
G	–
K_0	$0.6_{\pm 0.05}$ mm
P_0	$4.0_{\pm 0.1}$ mm

P_1	$2.0_{\pm 0.1}$ mm
P_2	$2.0_{\pm 0.05}$ mm
T	$0.25_{\pm 0.03}$ mm
W	$8.0_{+0.3/-0.1}$ mm

Table 1: Tape dimensions.

12.2 Reel with diameter of 180 mm

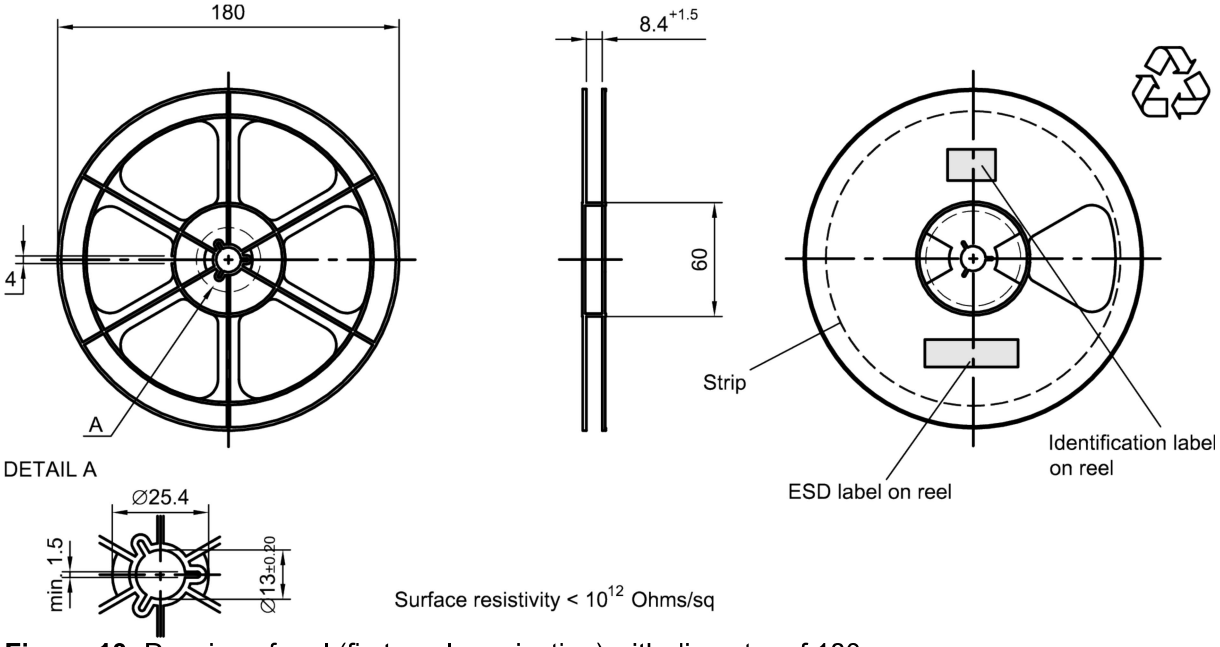


Figure 10: Drawing of reel (first-angle projection) with diameter of 180 mm.

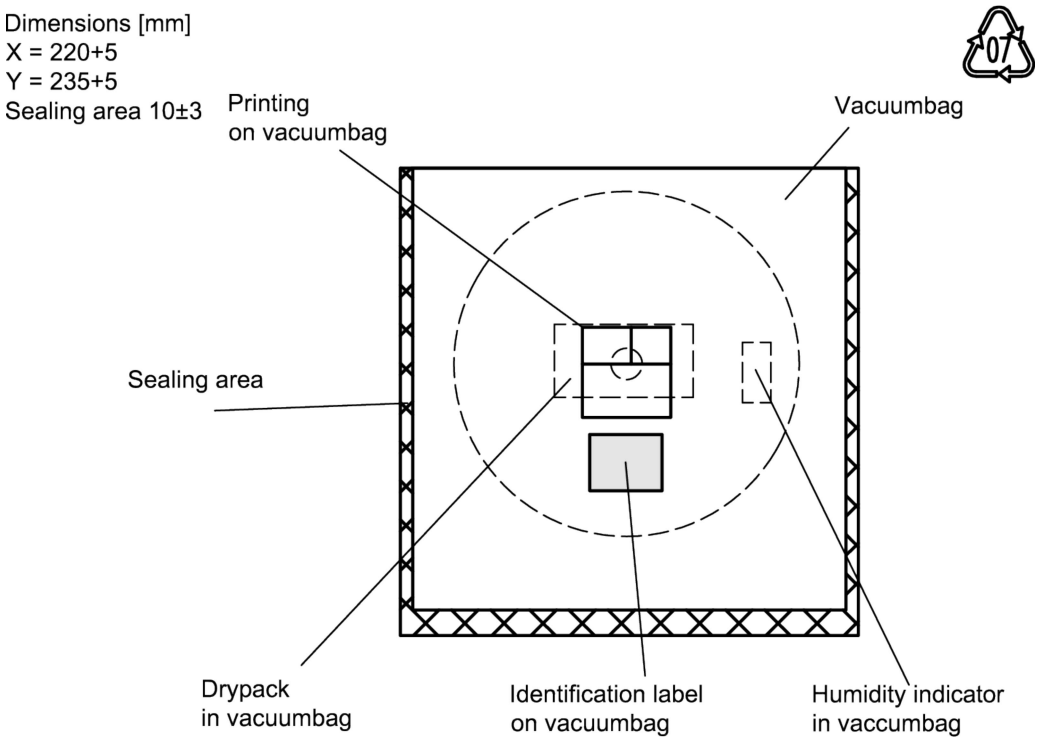


Figure 11: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

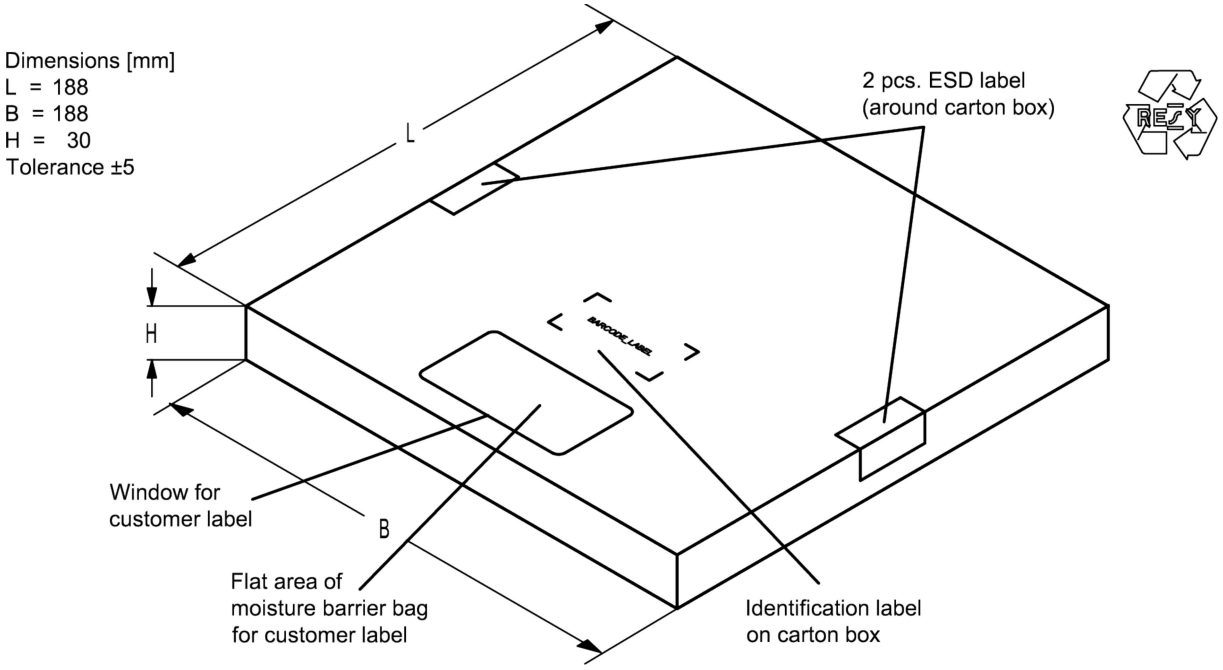


Figure 12: Drawing of folding box for reel with diameter of 180 mm.

13 Marking

Products are marked with product type number and lot number encoded according to Table 2:

- Type number:

  The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
  is encoded by a special BASE32 code into a 3 digit marking.

  Example of decoding type number marking on device in decimal code.
  16J **=>** **1234**
  1 x 32^2 + **6** x 32^1 + **18 (=J)** x 32^0 **=** **1234**
  The BASE32 code for product type B2614 is 2HP.

- Lot number:

  The last 5 digits of the lot number, e.g., **12345**,
  are encoded based on a special BASE47 code into a 3 digit marking.

  Example of decoding lot number marking on device in decimal code.
  5UY **=>** **12345**
  5 x 47^2 + **27 (=U)** x 47^1 + **31 (=Y)** x 47^0 **=** **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

14 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

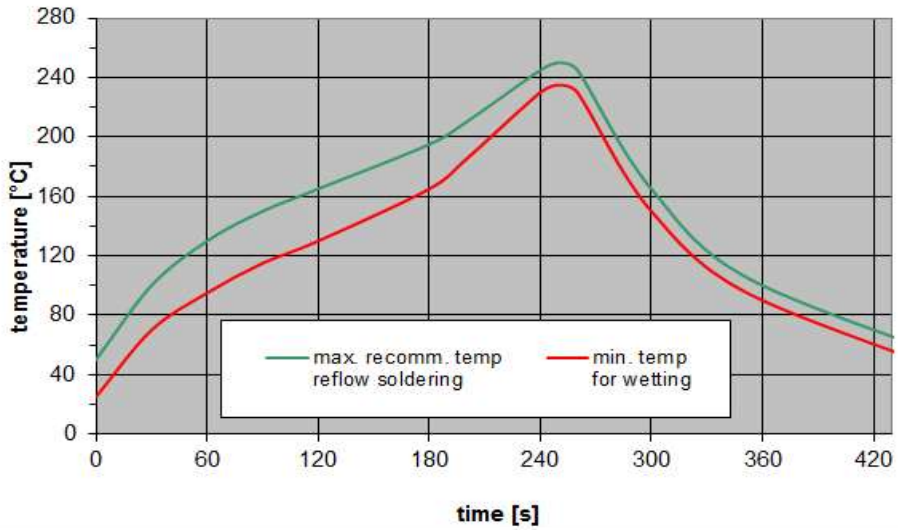


Figure 13: Recommended reflow profile for convection and infrared soldering – lead-free solder.

15 Annotations

15.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

15.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

16 Cautions and warnings

16.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

16.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

16.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

16.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

17 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.** As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
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